

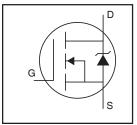
Features

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified *

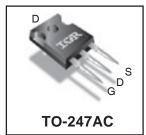
Description

Specifically designed for Automotive applications, this Cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low onresistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

HEXFET® Power MOSFET



V _{(BR)DSS}	55V
R _{DS(on)} max.	0.008 Ω
I _D	110A®



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	110 S	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	80 ⑤	Α
I _{DM}	Pulsed Drain Current ①	390	
P _D @T _C = 25°C	Power Dissipation	200	W
	Linear Derating Factor	1.3	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②	480	mJ
I _{AR}	Avalanche Current ①	59	Α
E _{AR}	Repetitive Avalanche Energy ①	20	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case		0.75	
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24		°C/W
$R_{\theta JA}$	Junction-to-Ambient		40	

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Static Electrical Characteristics @ T_J = 25℃ (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	55			٧	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.057		V/°C	Reference to 25°C, $I_D = 1mA$
R _{DS(on)}	Static Drain-to-Source On-Resistance			0.008	Ω	$V_{GS} = 10V, I_D = 59A \oplus$
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	٧	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
gfs	Forward Transconductance	42			S	$V_{DS} = 25V, I_{D} = 59A$
I _{DSS}	Drain-to-Source Leakage Current			25		$V_{DS} = 55V$, $V_{GS} = 0V$
				250	μΑ	$V_{DS} = 44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-100	IIA	V _{GS} = -20V

Dynamic Electrical Characteristics @ T₁ = 25℃ (unless otherwise specified)

		(.			/
Q_g	Total Gate Charge			170		I _D = 59A
Q_{gs}	Gate-to-Source Charge			32	nC	$V_{DS} = 44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge			74		V _{GS} = 10V,See Fig.6 and 13 ⊕
t _{d(on)}	Turn-On Delay Time		14			$V_{DD} = 28V$
t _r	Rise Time		100			$I_D = 59A$
t _{d(off)}	Turn-Off Delay Time		43		ns	$R_G = 2.5\Omega$
t _f	Fall Time		70			$R_D = 0.39\Omega$, See Fig. 10 \oplus
L _D	Internal Drain Inductance		5.0			Between lead,
			5.0		nH	6mm (0.25in.)
Ls	Internal Source Inductance		13		11111	from package
			13			and center of die contact
C _{iss}	Input Capacitance		4000			$V_{GS} = 0V$
C _{oss}	Output Capacitance		1300		pF	$V_{DS} = 25V$
C _{rss}	Reverse Transfer Capacitance		480			f = 1.0MHz,See Fig.5

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)			110⑤		MOSFET symbol showing the
I _{SM}	Pulsed Source Current			390	Α	integral reverse
	(Body Diode) ①			000		p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_{J} = 25^{\circ}C, I_{S} = 59A, V_{GS} = 0V \oplus$
t _{rr}	Reverse Recovery Time		110	170	ns	$T_J = 25^{\circ}C, I_F = 59A$
Q _{rr}	Reverse Recovery Charge		450	680	nC	di/dt = 100A/µs ④

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- © V_{DD} = 25V, starting T_J = 25°C, L = 190 μ H, R_G = 25 Ω , I_{AS} = 59A.(See Figure 12)
- 4 Pulse width \leq 300 $\mu s;$ duty cycle \leq 2%
- © Calculated continuous current based on maximum allowable junction temperature; for recommended current-handling of the package refere to Desing Tip # 93-4

Qualification Information[†]

		Automotive					
		(per AEC-Q101) ^{††}					
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.					
Moisture Sensitivity Level 3L-TO-247			N/A				
	Machine Model		Class M4(+/- 800V) ^{†††}				
		(per AEC-Q101-002)					
ESD	Human Body Model	Class H1B(+/- 4000V) 1+++					
LSD	,		(per AEC-Q101-001)				
			Class C5(+/- 2000V) ^{†††}				
	Charged Device Model	(per AEC-Q101-005)					
RoHS Complian	nt	Yes					

[†] Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

^{††} Exceptions to AEC-Q101 requirements are noted in the qualification report.

^{†††} Highest passing voltage

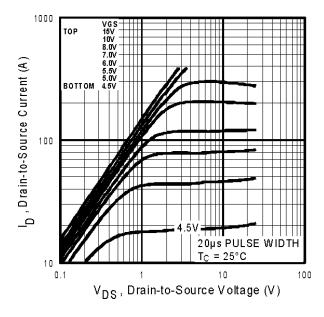


Fig 1. Typical Output Characteristics

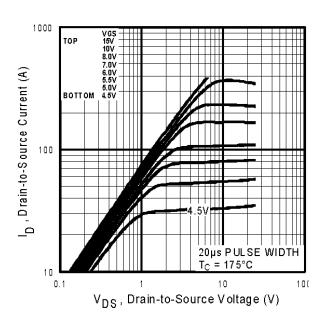


Fig 2. Typical Output Characteristics

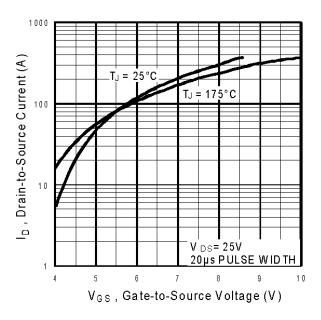


Fig 3. Typical Transfer Characteristics

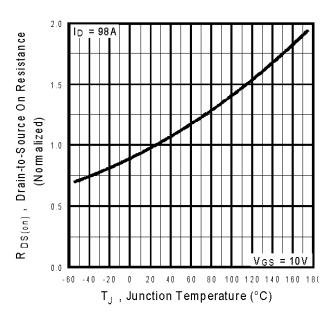


Fig 4. Normalized On-Resistance Vs. Temperature

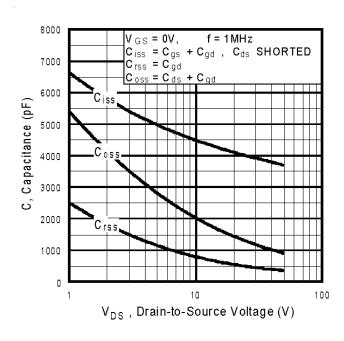


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

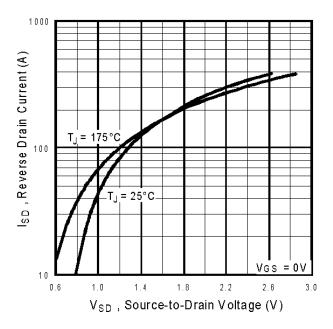


Fig 7. Typical Source-Drain Diode Forward Voltage

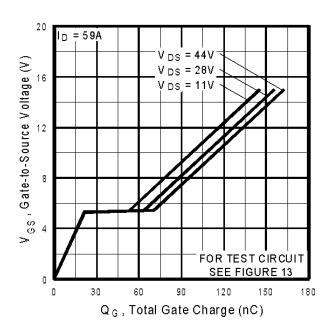


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

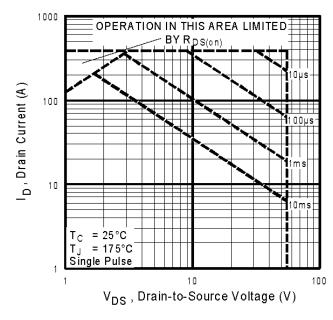
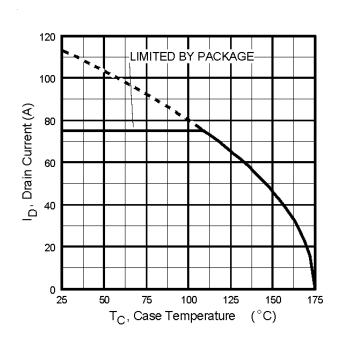


Fig 8. Maximum Safe Operating Area



 $\begin{array}{c|c} R_D \\ \hline V_{DS} \\ \hline \end{array}$ D.U.T. $\begin{array}{c|c} R_D \\ \hline \end{array}$ 10V $\begin{array}{c|c} Pulse \ \text{Width} \le 1 \ \mu s \\ Duty \ Factor \le 0.1 \ \% \end{array}$

Fig 10a. Switching Time Test Circuit

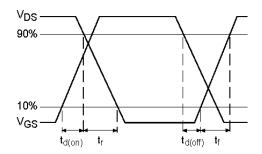


Fig 9. Maximum Drain Current Vs. Case Temperature

Fig 10b. Switching Time Waveforms

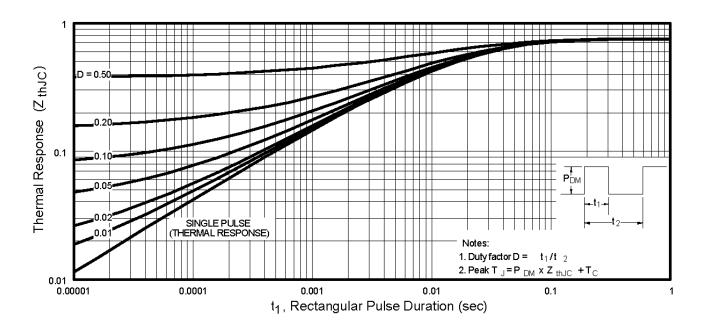


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

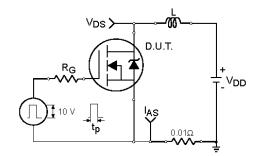


Fig 12a. Unclamped Inductive Test Circuit

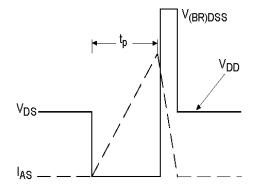


Fig 12b. Unclamped Inductive Waveforms

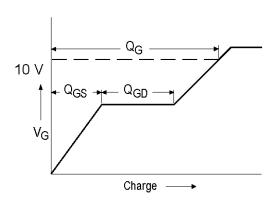


Fig 13a. Basic Gate Charge Waveform

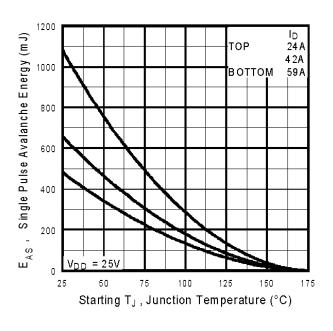


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

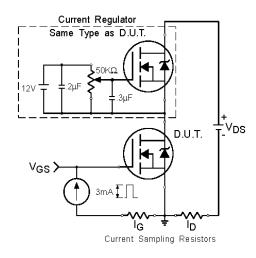
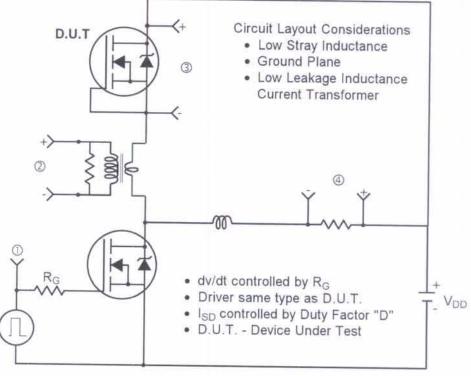


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit Circuit Layout Considerations



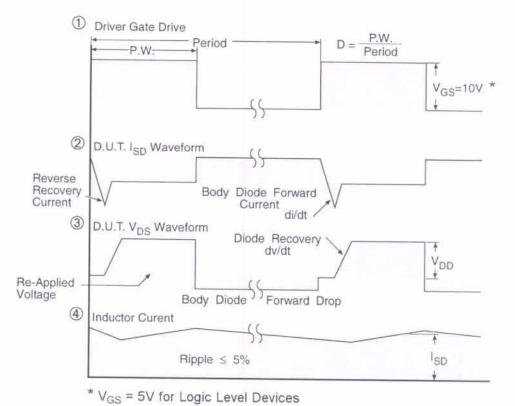
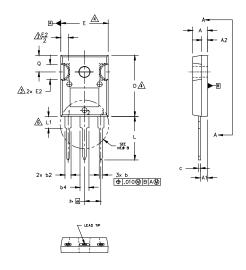
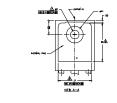


Fig 14. For N-Channel HEXFETS

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)









NOTES:

DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994

DIMENSIONS ARE SHOWN IN INCHES.

CONTOUR OF SLOT OPTIONAL.

DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED .005° (0.127)
PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.

LEAD FINISH UNCONTROLLED IN L1.

 $\ensuremath{\mathrm{oP}}$ TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 $^{\circ}$ TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.

OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AC

	DIMENSIONS				
SYMBOL	INC	HES	MILLIM	ETERS	1
	MIN.	MAX.	MIN,	MAX.	NOTES
A	.183	.209	4,65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1,50	2.49	
b	.039	.055	0.99	1,40	
ь1	.039	.053	0.99	1,35	
b2	.065	.094	1,65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3,38	
С	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19,71	20,70	4
D1	.515	-	13.08	-	5
D2	.020	.053	0.51	1,35	
E	.602	.625	15.29	15.87	4
E1	.530	-	13,46	-	
E2	.178	.216	4.52	5.49	
e	.215	BSC	5.46	BSC	
Øk	.0	10	0.	25]
L	.559	.634	14.20	16.10]
L1	.146	.169	3.71	4.29	
øΡ	.140	.144	3.56	3.66	1
øP1	-	.291	-	7,39	
Q	.209	.224	5.31	5.69	
S	.217	BSC	5.51	BSC]
			II.		

LEAD ASSIGNMENTS

<u>HEXFET</u>

- 1,- GATE 2.- DRAIN 3.- SOURCE 4.- DRAIN

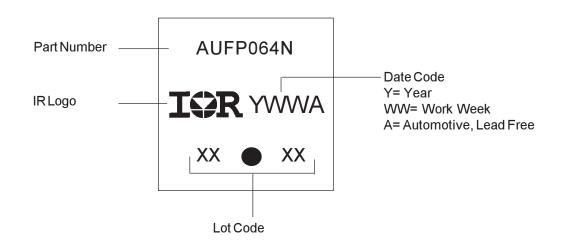
IGBTs, CoPACK

- 1.- GATE 2.- COLLECTOR 3.- EMITTER 4.- COLLECTOR

DIODES

- 1.- ANODE/OPEN 2.- CATHODE 3.- ANODE

TO-247AC Part Marking Information



Ordering Information

Base part	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFP064N	TO-247	Tube	25	AUIRFP064N

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For technical support, please contact IR's Technical Assistance Center http://www.irf.com/technical-info/

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